

[received by the International Bureau on 15 July 2005 (15.07.05)
original claims 11 is amended ;
original claims 1-10, and 12 – 16 are unchanged (2 pages)]

10. A polishing apparatus according to any one of claims 1 to 9, further comprising a pure water ejector for ejecting pure water into said polishing chamber so as to clean said polishing chamber.

5 11. (Amended) A substrate processing apparatus comprising:
a polishing unit for polishing a bevel portion of a substrate by bringing a
polishing tape into sliding contact with the bevel portion of the substrate;
a cleaning unit for cleaning at least the bevel portion of the substrate; and
a drying unit for drying the substrate which has been cleaned by said cleaning
10 unit;

wherein said polishing unit has a polishing chamber therein, and an internal pressure of said polishing chamber is set to be lower than an external pressure of said polishing chamber.

15 12. A substrate processing apparatus according to claim 11, wherein said polishing unit brings said polishing tape into sliding contact with the bevel portion and an edge portion of the substrate so as to polish the bevel portion and the edge portion.

20 13. A substrate processing apparatus according to claim 11 or 12, wherein said polishing unit brings a polishing tape into sliding contact with a notch portion of the substrate so as to polish the notch portion.

25 14. A substrate processing apparatus according to any one of claims 11 to 13, further comprising a partition which divides an internal space of said substrate processing apparatus into a polishing area for polishing the substrate and a cleaning area for cleaning the substrate, an internal pressure of said polishing area being set to be lower than an internal pressure of said cleaning area.

30 15. A substrate processing apparatus according to claim 14, further comprising a fan unit for forming a downward current of a clean gas in said cleaning area.

16. A substrate processing apparatus according to any one of claims 11 to 15, further comprising a chemical mechanical polishing unit for polishing a surface of the

substrate by pressing the substrate against a polishing table.